Kulicke & Soffa to Participate and Host Technical Seminar at SEMICON Taiwan 2016

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SEMICON Taiwan 2016 trade show in Taipei, Taiwan, from September 7 to 9, 2016.

Kulicke & Soffa will be showcasing its market leading packaging solutions at Taipei Nangang Exhibition Center, 4F, Booth Number 430.

- AsterionTM EV, an extended version of the Asterion wedge bonder built on a new architecture with enhanced capability to handle a multitude of interconnect materials. It offers an expanded bond area with new robust pattern recognition capabilities and extremely tight process controls for advanced interconnect materials. These advanced features deliver heightened productivity, bonding quality and reliability. The enlarged bondable area enhances flexibility and productivity, directly benefiting cost of ownership.
- Hybrid, a multi-application solution for advanced packaging, ideal for wafer level packaging,Fan-Out Wafer Level Packaging (FOWLP), System-in-Package (SiP), Multi-Chip Module (MCM), flip-chip, modules and embedded components. With the Hybrid's new TPR (Twin Placement Robot), the placement accuracy has improved to 7µm. It is highly capable of placing both active and passive components, achieving a throughput up to 27K UPH for Flip Chips plus 48K UPH for passives with a single machine.
- IConnPS MEM PLUSTM, a high performance Memory bonder for Gold and Silver alloy wire bonding. With its advanced process, looping overhang and ease of use capabilities, it delivers high quality and productivity benefits in complex multistack package applications.
- AT PremierPS PLUSTM, a versatile wafer level bonder for wire bonding and stud bumping applications. It delivers high productivity and increased efficiency with its low temperature gold stud-bumping capabilities.

Yih-Neng Lee, Kulicke & Soffa's Senior Vice President of Global Sales and Services, said, "The back-end semiconductor market continues to evolve rapidly, increasing demand and creativity in the assembly and packaging technologies. K&S is well positioned to address these new challenges and continues to invest at the fore-front of technology."

Kulicke & Soffa will be holding a technical seminar during the SEMICON Taiwan trade show on September 7, 2016, at Nangang Exhibition Hall, 6F, 616 Meeting Room.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

View source version
on businesswire.com: http://www.businesswire.com/news/home/20160901005122/en/

Kulicke & Soffa Industries, Inc.
Marilyn Sim
Public Relations
P: +65-6880-9309
F: +65-6880-9580
msim@kns.com
or
Joseph Elgindy
Investor Relations & Strategic Initiatives
P: +1-215-784-7500
P: +31-40-272-3016
F: +1-215-784-6180
investor@kns.com
